



Patent  
Case No.: 58373US002

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

First Named Inventor: SHEEHAN, RICHARD L. JR.

Application No.: 10/705499 Group Art Unit: Unknown

Filed: November 10, 2003 Examiner: Unknown

Title: A CONTAINER FOR CONTAINING SEMICONDUCTOR WAFERS

**INFORMATION DISCLOSURE STATEMENT**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

**CERTIFICATE OF MAILING**  
I hereby certify that this correspondence is being deposited with the United States Postal Service as First Class Mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on:

February 13, 2004  
Date

*Colleen M. Wagner*  
Signed by: Colleen M. Wagner

Dear Sir:

Pursuant to 37 CFR §§ 1.56, 1.97, and 1.98, enclosed is a completed Form PTO-1449, citing references submitted for consideration by the Examiner. Copies of any cited foreign patents, non-patent literature, and unpublished US application documents are enclosed. Pursuant to the waiver in the Pre-OG Notice, dated July 11, 2003, copies of US patents and published US patent applications are no longer required and are not enclosed. It is respectfully requested that the Examiner initial and return the enclosed Form PTO-1449 to indicate that each reference has been considered.

If a first Office Action on the merits has been mailed prior to the mailing date of this document, please charge the fee for consideration of an Information Disclosure Statement set forth in 37 CFR § 1.17(p), and if necessary, please charge any additional fees, or credit any overpayment to Deposit Account No. 13-3723.

Respectfully submitted,

By: *Melissa E. Buss*  
Melissa E. Buss, Reg. No. 47,465  
Telephone No.: (651) 733-0649

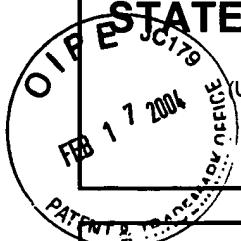
February 12, 2004

Date

# INFORMATION DISCLOSURE STATEMENT BY APPLICANT

(Use as many sheets as necessary)

Page 1 of 3



## U.S. Patent Documents

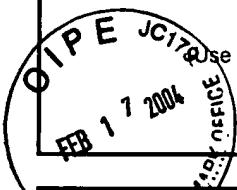
Exam. Init.*	Cite No.	Document Number	Publication Date or Issue Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear
		Doc. Number-(Kind Code if Known)			
	A1	US- 3,148,822	09/15/1964	Yochum, Jr.	
	A2	US- 4,003,468	01/18/1977	Berkman	
	A3	US- 4,253,571	03/03/1981	Keohan	
	A4	US- 4,482,074	11/13/1984	Lalley	
	A5	US- 4,708,246	11/24/1987	Minion	
	A6	US- 4,787,508	11/29/1988	Wu et al.	
	A7	US- 4,793,123	12/27/1988	Pharo	
	A8	US- 4,883,178	11/28/1989	Thiele et al.	
	A9	US- 4,872,558	10/10/1989	Pharo	
	A10	US- 4,874,093	10/17/1989	Pharo	
	A11	US- 4,918,904	04/24/1990	Pharo	
	A12	US- 4,949,530	08/21/1990	Pharo	
	A13	US- 5,007,536	04/16/1991	Huebner et al.	
	A14	US- 5,253,756	10/19/1993	Goekler	
	A15	US- 5,272,856	12/28/1993	Pharo	
	A16	US- 5,303,823	04/19/1994	Niles et al.	
	A17	US- 5,310,070	05/10/1994	Haas et al.	
	A18	US- 5,366,079	11/22/1994	Lin et al.	
	A19	US- 5,427,830	06/27/1995	Pharo	
	A20	US- 5,445,274	08/29/1995	Pharo	
	A21	US- 5,487,470	01/30/1996	Pharo	
	A22	US- 5,501,351	03/26/1996	Niles	
	A23	US- 5,553,711	09/10/1996	Lin et al.	
	A24	US- 5,586,658	12/24/1996	Nyseth	
	A25	US- 5,699,916	12/23/1997	Liang	
	A26	US- 5,780,127	07/14/1998	Mikkelsen	
	A27	US- 5,782,362	07/21/1998	Ohori	
	A28	US- 5,788,082	08/04/1998	Nyseth	

\*Examiner:

Date Considered:

EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

## INFORMATION DISCLOSURE STATEMENT BY APPLICANT



(Use as many sheets as necessary)

Page 2 of 3

## U.S. Patent Documents

Exam. Init.*	Cite No.	Document Number	Publication Date or Issue Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear
		Doc. Number-(Kind Code if Known)			
	A29	US- 5,788,304	08/04/1998	Korn et al.	
	A30	US- 5,833,067	11/10/1998	Joshi	
	A31	US- 5,875,896	03/02/1999	Liang	
	A32	US- 6,119,865	09/19/2000	Kawada	
	A33	US- 6,193,068 B1	02/27/2001	Lewis et al.	
	A34	US- 6,193,090 B1	02/27/2001	Connors et al.	
	A35	US- 6,283,296	09/04/2001	Newman	
	A36	US- 6,286,684 B1	09/11/2001	Brooks et al.	
	A37	US- 6,464,079 B1	10/15/2002	Newman	

## Foreign Patent Documents

Exam. Init.*	Cite No.	Foreign Patent Document		Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear	Translation (Check if yes)
		Ctry. Code	Number-KindCode (If known)				
	B1	EP	0 789 393 A1	08/13/1997			
	B2	GB	2 293 816 A	04/10/1996			
X	B3	WO	01/07339 A1	02/01/2001			
X	B4	WO	01/92135 A1	12/06/2001			
X	B5	WO	02/79053 A1	10/10/2002			

## OTHER PRIOR ART -- NON PATENT LITERATURE DOCUMENTS

Exam. Init.*	Cite No.	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published
	C1	"Semiconductor Wafer Shipping and Storage Systems", Malaster Company Inc., Sunnyvale, CA, USA, [retrieved on the internet on November 10, 2003], < <a href="http://www.malaster.com/wafer.htm">http://www.malaster.com/wafer.htm</a> >, pp. 4.
	C2	"250 Series Wafer Transport Carriers", Entegris, Inc., Chaska, MN, USA, [retrieved on the internet on November 10, 2003], < <a href="http://www.wafercare.com/Default.asp?G=87">http://www.wafercare.com/Default.asp?G=87</a> >, pp. 4.
	C3	"Reducing Wafer Damage During Shipping", Entegris, Inc., Chaska, MN, USA, 2001, pp. 3.
	C4	"Wafer Shipping System", SPI/Semicon, Ogden, UT, USA, [retrieved on the internet on November 10, 2003], < <a href="http://www.spisemicon.com/wafersystems.htm">http://www.spisemicon.com/wafersystems.htm</a> >, pp.2.
	C5	"Packing and shipping – Material integrity issue", Entegris, Inc., Chaska, MN, USA, [retrieved on the internet on November 10, 2003], < <a href="http://www.entegris.com/pdf/tech/1310-0948.pdf">http://www.entegris.com/pdf/tech/1310-0948.pdf</a> >, pp.4.

*Don't receive marked \**

Examiner:

Date Considered:

EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

## INFORMATION DISCLOSURE STATEMENT BY APPLICANT

(Use as many sheets as necessary)

Page 3 of 3

## OTHER PRIOR ART -- NON PATENT LITERATURE DOCUMENTS

Exam. Init.*	Cite No.	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published
	C6	"300mm Horizontal Wafer Shipper (HWS) System", Entegris, Inc. Chaska, MN, USA, [retrieved on the internet on November 13, 2003], < <a href="http://www.devicecare.com/Default.asp?Page=HWSItems&amp;WaferSize=300">http://www.devicecare.com/Default.asp?Page=HWSItems&amp;WaferSize=300</a> >, pp.4.
	C7	"CEN' Wafer Shipping System – Innovative Solutions for Delicate Wafer Handling & Shipping", SPI/Semicon, Ogden, UT, USA, pp. 1.
	C8	"Horizontal Wafer Shippers", Central Corporation, Yamanashi, Japan, [retrieved on the internet on May 22, 2002], < <a href="http://www.central-corp.com/semi/wafercarriers.htm">http://www.central-corp.com/semi/wafercarriers.htm</a> >, pp. 2.
	C9	Flyer entitled, "Spec The 3M Wafer Transport System And Get Your Earthly Reward", 3M Packaging Systems.
	C10	3M Company, "Wafer Transport System – Your Complete Wafer Transport Management Solution" Brochure, Packaging Systems Division, © 2002.
	C11	3M Company, "Air Cushion Packaging for Wafer Transport System" Brochure, Industrial Services and Solutions Division, © 2002.
	C12	3M Company, "150 mm Wafer Separator" Brochure, Packaging Systems Division, © 2002.
	C13	3M Company, "Horizontal 150 mm Wafer Shipper" Brochure, Packaging Systems Division, © 2002.
	C14	3M Company, "Open Cell Foam Pad for Horizontal 150 mm Wafer Shipper" Brochure, Packaging Systems Division, © 2002.
	C15	FR 2246458 French reference, inventor; Hefendehl, date: May 1975 drawings and Abstract (no spec. and no claims)
	C16	Alberghini et al., "Technology, Performance, Markets, Economics – The Complete Blow Molding Operation", Blow Molding Handbook, pp. 15-52, 1988.
	C17	Kirkham et al., "Injection molding", Modern Plastics, Mid-October Encyclopedia Issue, pp. 286-296, 1989.
	C18	Whiteside, "Theromoforming", Modern Plastics, Mid-October Encyclopedia Issue, pp. 318-322, 1989.

\*Examiner:

Date Considered:

EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.